

U RESIN 2473



U RESIN 2473 Epoxy Casting Compound is a 100% solids epoxy casting compound system which can be used to encapsulate a wide range of materials particularly electrical components. Typical applications include electrical encapsulation, mould backing and moulded epoxy components.

U RESIN 2473 Epoxy Casting Compound is a two pack epoxy which is easily poured when mixed and can have a variety of fillers added to it. U RESIN 2473 Casting Compound has good resistance to chemicals. The two components can be mixed using a spatula or stirrer until a uniform grey colour is obtained.

One of the great features of U RESIN 2473 when mixed, develops a very low exothermic (heat) reaction. This low exothermic reaction is necessary when working with heat-sensitive components. This leads to lower shrinkage and greater compressive strength. The mix will cure at room temperature.

PROFILE:

	PART A	PART B	MIXED
Colour	OFF WHITE	BLACK	GREY
Mix Ration (by Weight)	2	1	
Pot Life @ 25°C (mins)			45
Tensile Strength			50MPa
Specific Gravity			1.05
Flexural Strength			35MPa
Hardness (Shore D)			75-80

SURFACE PREPARATION

The surface should be free of loose material and all foreign matter such as dirt, oil and other contaminants. A solvent such as acetone may be used to clean the surface.

PREPARATION

It is important that the correct mix ratio is used and that the resin and hardener are thoroughly stirred before use and accurately weighed out.

MIXING

Mix both components together until a homogenous mix has been achieved. Be sure to scrape the sides and bottom of the mixing vessel to ensure this.

FEATURES

- Free of all Solvents
- Easy to Pour
- High Mechanical Strength
- Bonds to a wide range of materials and substrates
- Rated Non DG for transport

The information contained herein is true and accurate, based on laboratory conditions. It is recommended that the user contact the manufacturer to confirm suitability as field conditions may vary and yield different results. Testing of this product is strongly recommended to confirm suitability for specific applications. Data should not be used for specification purposes.